

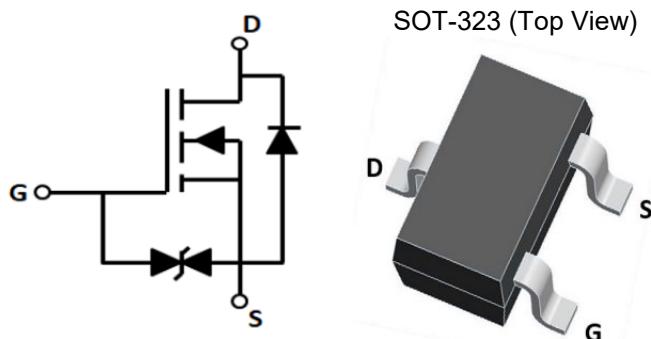
Description

CM2N7002DW is the N-Channel enhancement mode power field effect transistors with high cell density, trench technology. This high density process and design have been optimized switching performance and especially tailored to minimize on-state resistance.

Features

- V_{DS}: 60V
- I_D: 300mA
- R_{DS(on)} (@V_{GS}=10V) : < 2.5Ω
- R_{DS(on)} (@V_{GS}=4.5V) : < 3.0Ω
- High density cell design for extremely low R_{DS(on)}
- Excellent on-resistance and DC current capability

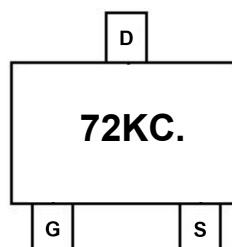
Equivalent Circuit and Pin Configuration



Applications

- Cellular Handsets and Accessories
- Personal Digital Assistants
- Portable Instrumentation
- Load switch

Marking Information



Marking Code = 72KC.

Ordering Information

| Part Number | Packaging | Reel Size |
|-------------|------------------|-----------|
| CM2N7002DW | 3000/Tape & Reel | 7 inch |

Absolute Maximum Ratings (TA=25 °C unless otherwise noted)

| Parameter | | Symbol | Maximum | Unit |
|---|---------|----------------------|-------------|------|
| Drain-source Voltage | | V _{DS} | 60 | V |
| Gate-source Voltage | | V _{GS} | ±20 | V |
| Continuous Drain Current | TA=25°C | I _D | 300 | mA |
| | TA=70°C | | 240 | mA |
| Pulsed Drain Current ⁽¹⁾ | | I _{DM} | 1.5 | A |
| Total Power Dissipation @ TA=25°C ⁽²⁾ | | P _D | 300 | mW |
| Thermal Resistance Junction-to-Ambient ⁽²⁾ | | R _{θJA} | 416 | °C/W |
| Junction and Storage Temperature Range | | T _{J,T STG} | -55 to +150 | °C |

Electrical Characteristics (T_J=25 °C unless otherwise noted)

| Parameter | Symbol | Conditions | Min | Typ | Max | Units |
|---------------------------------------|---------------------|---|-----|------|-----|-------|
| Static Parameter | | | | | | |
| Drain-Source Breakdown Voltage | BVDSS | V _{GS} =0V, I _D =250μA | 60 | | | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =60V, V _{GS} =0V, T _C =25°C | | 1 | | μA |
| Gate-Body Leakage Current | I _{GSS} | V _{GS} =±20V, V _{DS} =0V | | | ±10 | μA |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} , I _D =250μA | 1.0 | | 2.5 | V |
| Static Drain-Source on-Resistance | R _{DS(on)} | V _{GS} =10V, I _D =300mA | | 1.9 | 2.5 | Ω |
| | | V _{GS} =4.5V, I _D =200mA | | 2.0 | 3.0 | |
| Diode Forward Voltage | V _{SD} | I _S =300mA, V _{GS} =0V | | | 1.2 | V |
| Maximum Body-Diode Continuous Current | I _S | | | | 300 | mA |
| Dynamic Parameters | | | | | | |
| Input Capacitance | C _{iss} | V _{DS} =30V, V _{GS} =0V, f=1MHz | | 28 | | pF |
| Output Capacitance | C _{oss} | | | 4 | | |
| Reverse Transfer Capacitance | C _{rss} | | | 3 | | |
| Switching Parameters | | | | | | |
| Total Gate Charge | Q _g | V _{GS} =10V, V _{DS} =30V, I _D =0.3A | | 1.70 | | nC |
| Gate Source Charge | Q _{gs} | | | 0.35 | | |
| Gate Drain Charge | Q _{gd} | | | 0.55 | | |
| Turn-on Delay Time | t _{D(on)} | V _{GS} =10V, V _{DD} =30V, I _D =0.3A, R _{GEN} =6Ω | | 5 | | ns |
| Turn-off Delay Time | t _{D(off)} | | | 10 | | |

Noted: (1) Pulse Test: Pulse Width≤300us,Duty cycle ≤2%.

(2) Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch. With 2oz Copper ,t≤10s

Typical Performance Characteristics

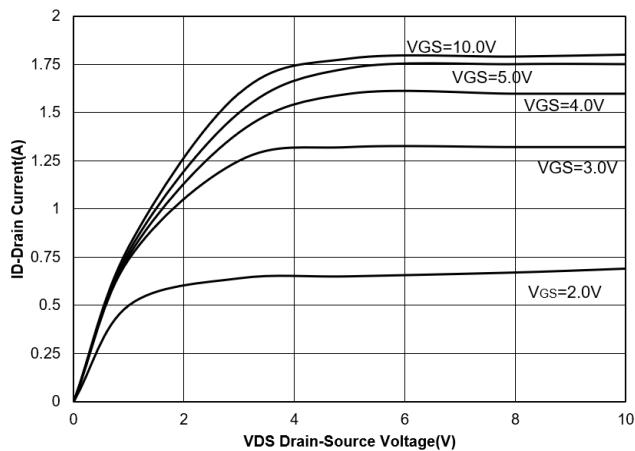


Figure 1. Output Characteristics

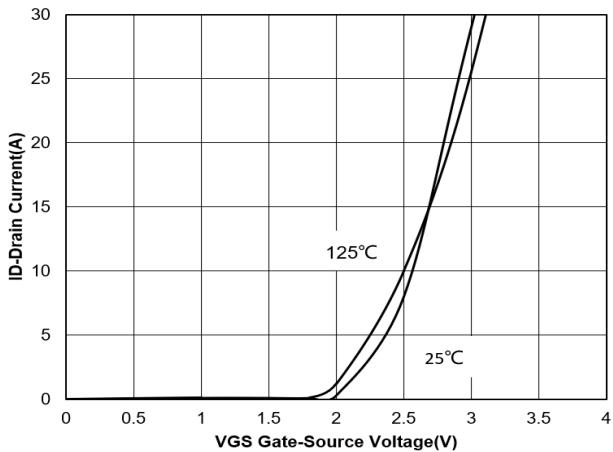


Figure 2. Transfer Characteristics

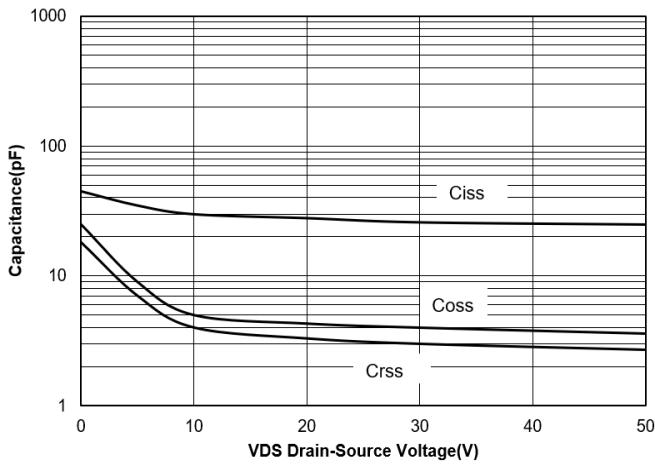


Figure 3. Capacitance Characteristics

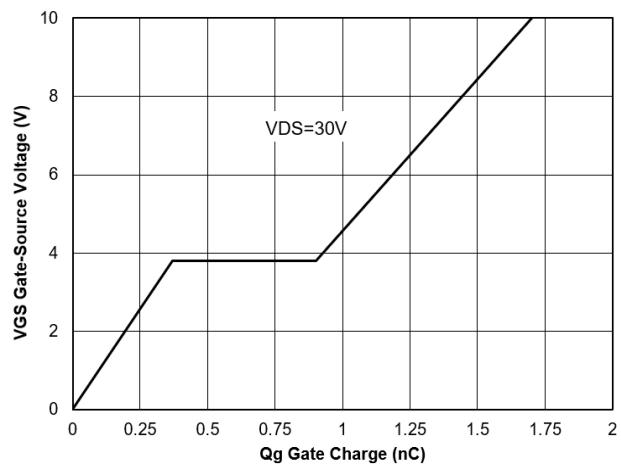


Figure 4. Gate Charge

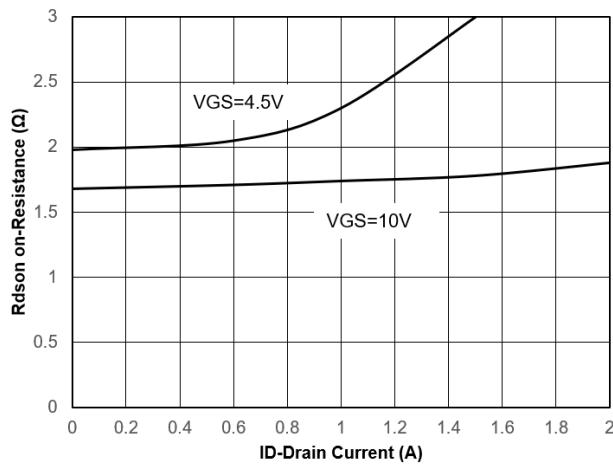


Figure 5. Drain-Source on Resistance

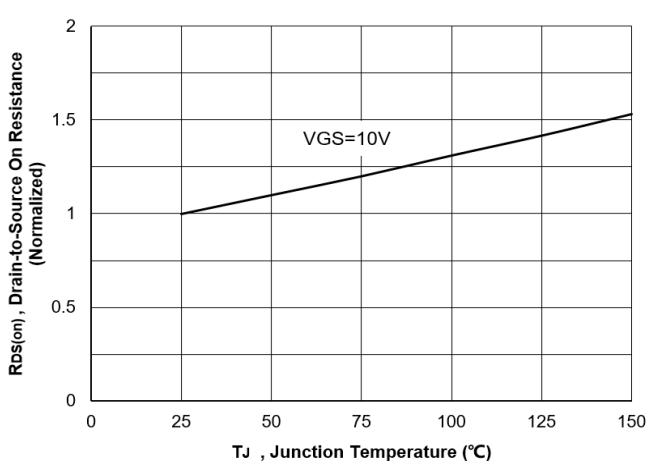


Figure 6. Normalized On-Resistance
Vs. Temperature

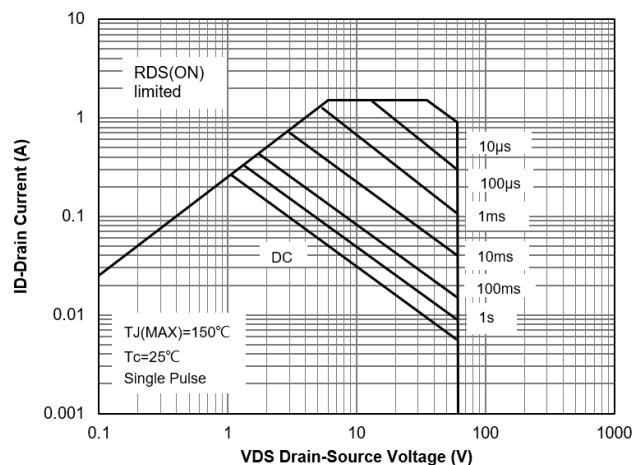


Figure 7. Safe Operation Area

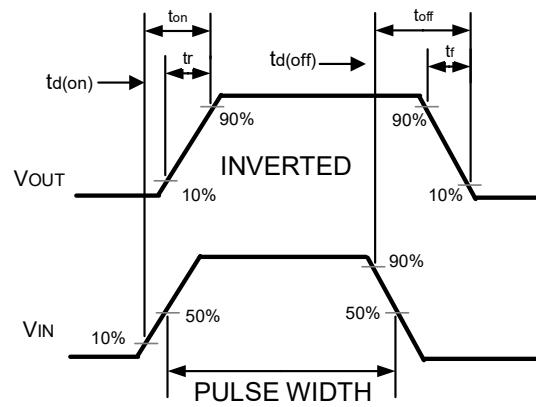


Figure 8. Switching wave

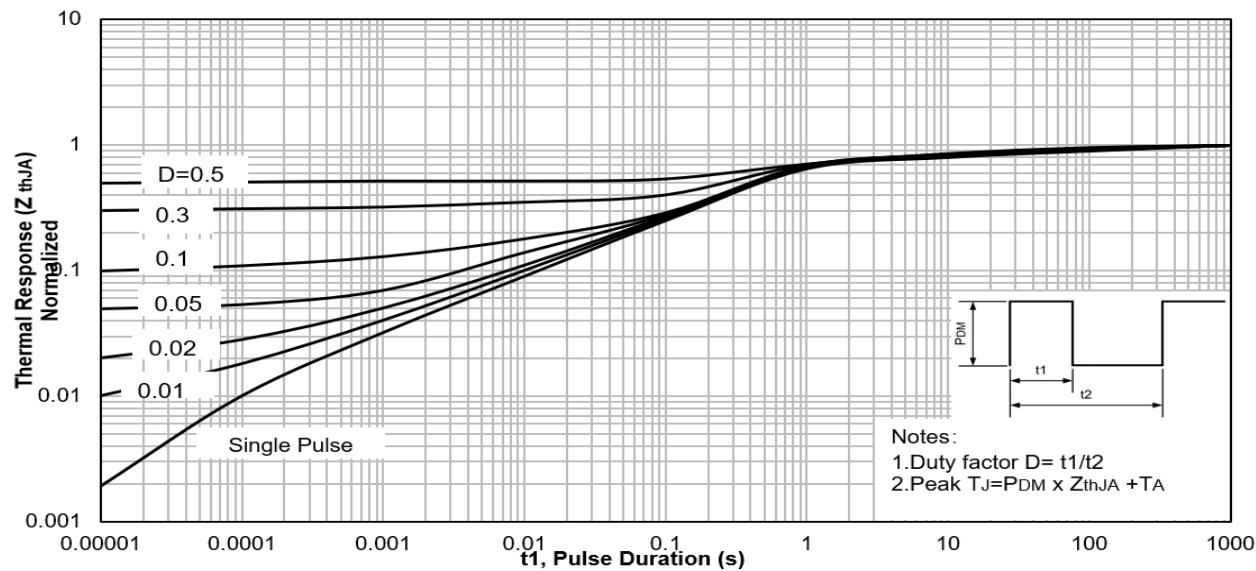
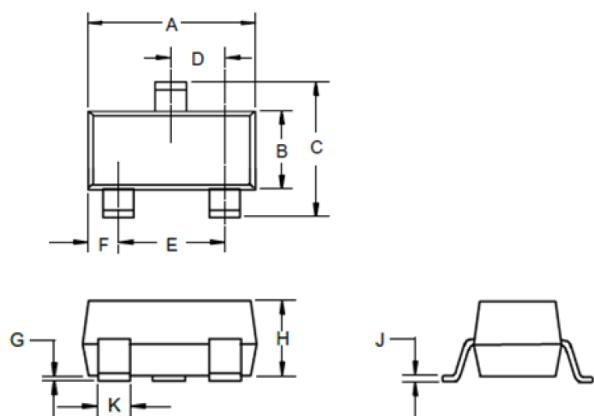


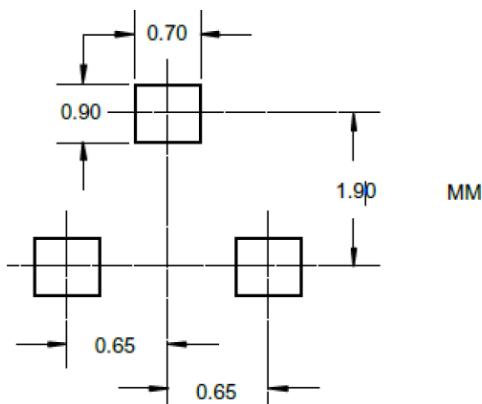
Figure 9. Maximum Effective Transient Thermal Impedance ,Junction-to-Ambient

SOT-323 Package Outline Drawing



| SYM | DIMENSIONS | | | |
|-----|--------------|------|---------------|-------|
| | MILLIMETERS | | INCHES | |
| | MIN | MAX | MIN | MAX |
| A | 1.80 | 2.20 | 0.071 | 0.087 |
| B | 1.15 | 1.35 | 0.045 | 0.053 |
| C | 2.10 | 2.45 | 0.083 | 0.096 |
| D | 0.65 Nominal | | 0.025 Nominal | |
| E | 1.20 | 1.40 | 0.047 | 0.055 |
| F | 0.30 | 0.40 | 0.012 | 0.016 |
| G | 0.00 | 0.10 | 0.000 | 0.004 |
| H | 0.90 | 1.00 | 0.035 | 0.039 |
| J | 0.10 | 0.25 | 0.004 | 0.010 |
| K | 0.15 | 0.40 | 0.006 | 0.016 |

Suggested Land Pattern



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